



**BRIGHTTEK**  
**BRIGHTTEK (EUROPE) LIMITED**

*Brighten Up The World With LED!*



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

## PRODUCT DATASHEET

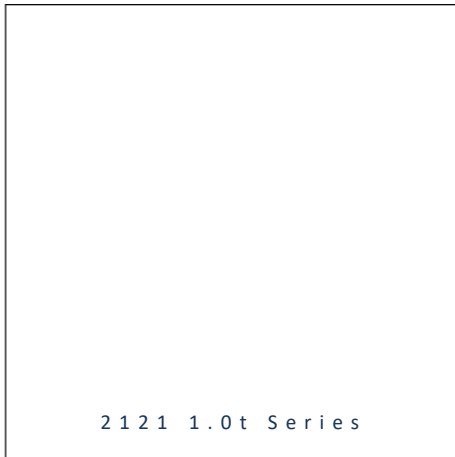


- ▶ PLCC4 SMD Top View
- ▶ 2121 1.0t Series
- ▶ Red / Green / Blue

NOM67S70BS



Release Date: 15 October 2024 Version: A1.0



2121 1.0t Series

### 2121 1.0t Series

**RoHS**  
Compliant



#### FEATURES (Red/Green/Blue\*):

- **Package:** PLCC4 RGB Black Face Top View SMD Package
- **Forward Current:** 20/20/20mA
- **Forward Voltage (typ.):** 2.1/3.0/3.0V
- **Luminous Flux (typ.):** 600/1550/500mcd@20mA
- **Colour:** Red/Green/Blue
- **Dominant Wavelength (typ.):** 622/525/467nm
- **Viewing angle:** 120/120/120°
- **Materials:**
  - Die: AlGaInP/InGaN/InGaN
  - Resin: Silicon (Water Clear)
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Grouping parameters:**
  - Forward voltage
  - Luminous intensity
  - Dominant wavelength
- **Soldering Methods:** IR Reflow soldering
- **MSL Level:** 5a according to JEDEC
- **Packing:** 8mm tape with max.4000pcs/reel, ø179mm (7")

#### APPLICATIONS:

- LED Display
- Switch Light
- 3C Application
- Decoration Lighting

## CHARACTERISTICS:

### Absolute Maximum Characteristics (T<sub>a</sub>=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I <sub>F</sub>	20/20/20*	mA
Pulse Forward Current (duty 1/10; width 0.1ms)	I <sub>MAX</sub>	30/30/30	mA
Power Dissipation	P <sub>o</sub>	48/68/68	mW
Reverse Voltage	V <sub>R</sub>	5/5/5	V
Reverse Current @5V	I <sub>R</sub>	5/5/5	μA
Operating Temperature	T <sub>OPR</sub>	-40~+85	°C
Storage Temperature	T <sub>STG</sub>	-40~+100	°C

1. \* In the order of Red/Green/Blue.

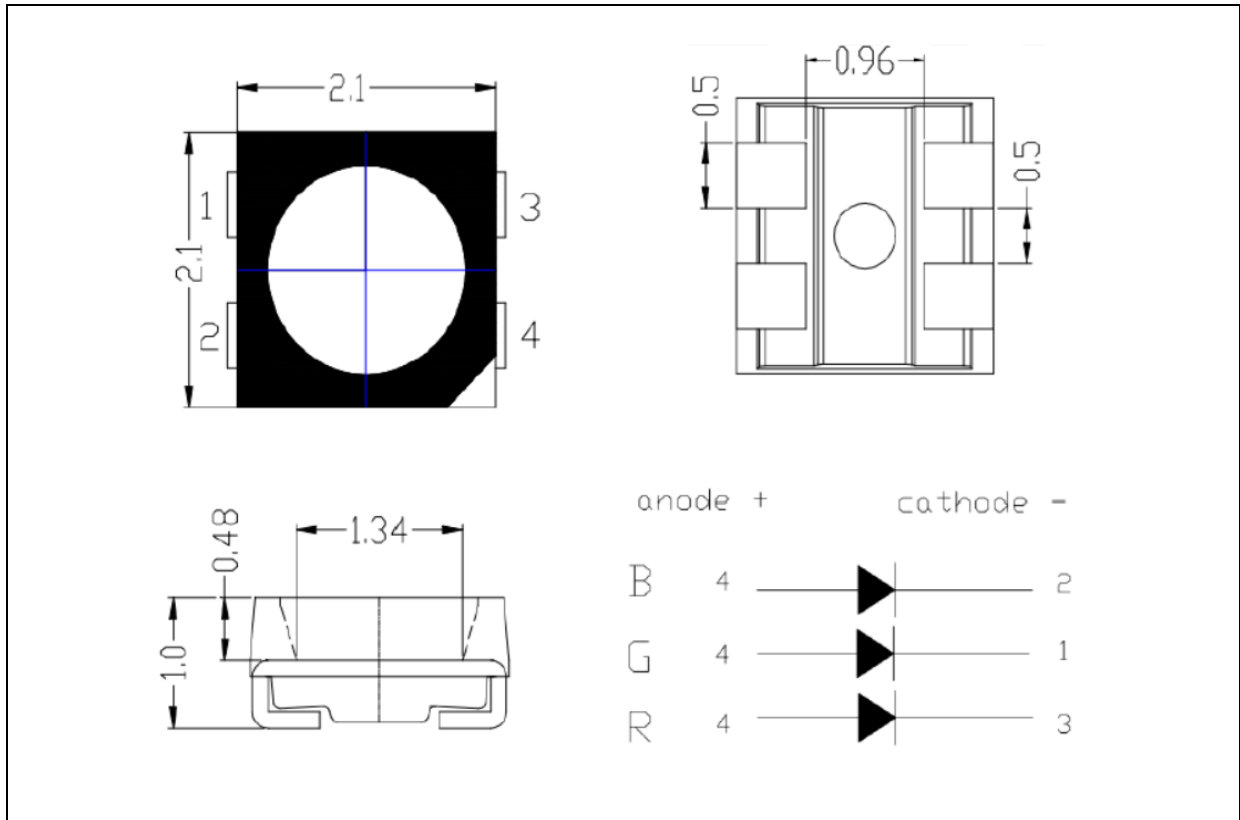
### Electrical & Optical Characteristics (T<sub>a</sub>=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Red - Forward Voltage	V <sub>F</sub>	1.8	---	2.4	V	I <sub>F</sub> =20mA
Red - Luminous Intensity	I <sub>V</sub>	500	---	700	mcd	I <sub>F</sub> =20mA
Red - Wavelength	W <sub>P</sub>	620	---	625	nm	I <sub>F</sub> =20mA
Green - Forward Voltage	V <sub>F</sub>	2.6	---	3.4	V	I <sub>F</sub> =20mA
Green - Luminous Intensity	I <sub>V</sub>	1300	---	1800	mcd	I <sub>F</sub> =20mA
Green - Wavelength	W <sub>P</sub>	523	---	528	nm	I <sub>F</sub> =20mA
Blue - Forward Voltage	V <sub>F</sub>	2.6	---	3.4	V	I <sub>F</sub> =20mA
Blue - Luminous Intensity	I <sub>V</sub>	400	---	600	mcd	I <sub>F</sub> =20mA
Blue - Wavelength	W <sub>P</sub>	465	---	470	nm	I <sub>F</sub> =20mA
Viewing Angle	2θ <sub>1/2</sub>	---	120	---	deg	I <sub>F</sub> =20mA

1. Luminous intensity (I<sub>V</sub>) ±10%, Forward Voltage (V<sub>F</sub>) ±0.1V, Viewing angle(2θ<sub>1/2</sub>) ±5%, Wavelength (λ) ±1nm.

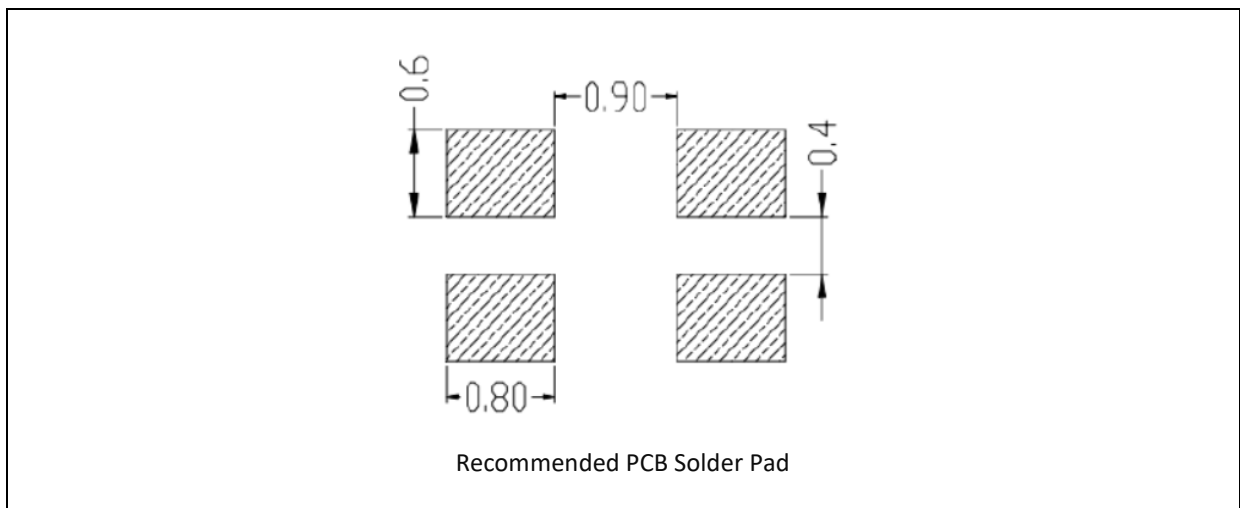
## OUTLINE DIMENSION:

Package Dimension:

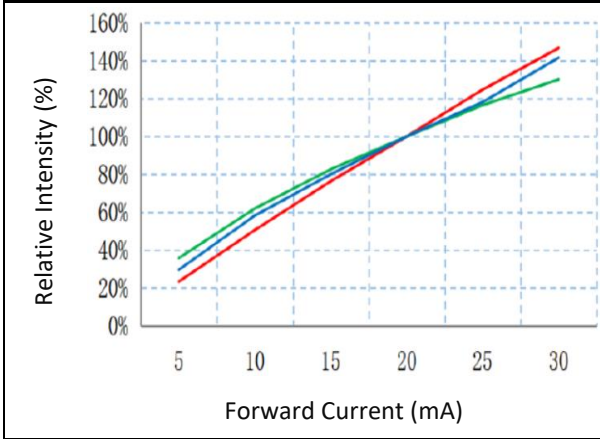
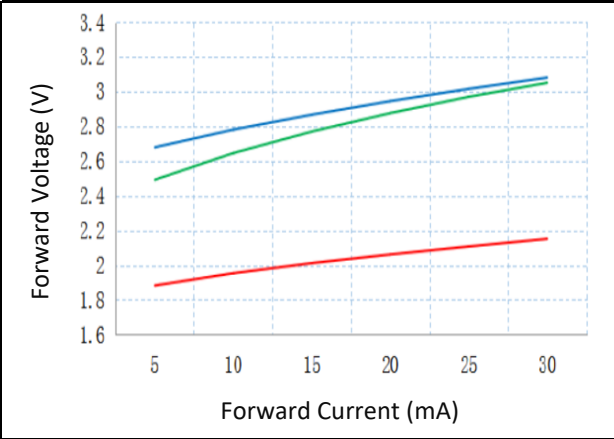
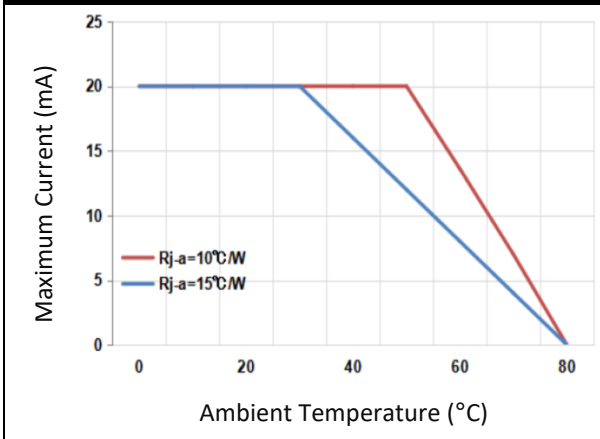
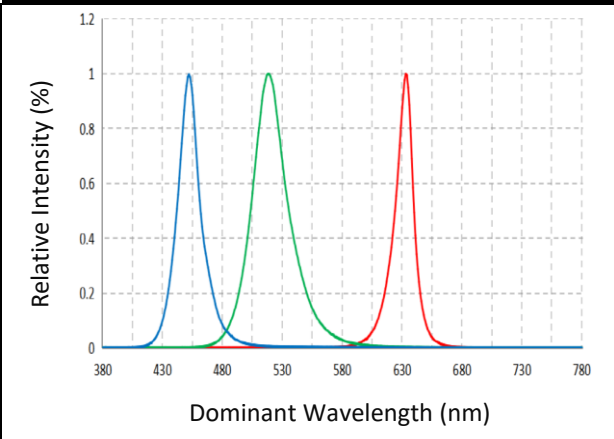
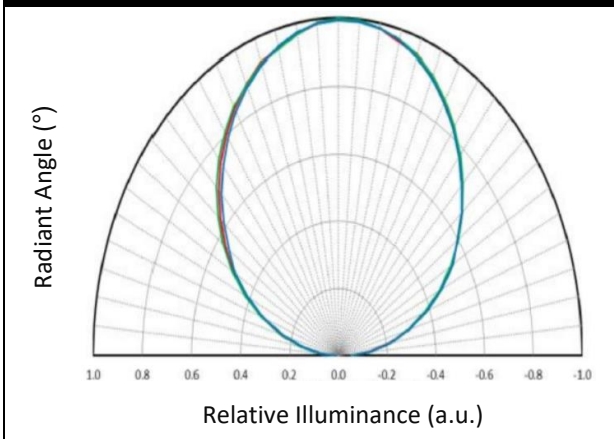


1. All dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.1\text{mm}$ , unless otherwise noted.

Recommended Soldering Pad Dimension:



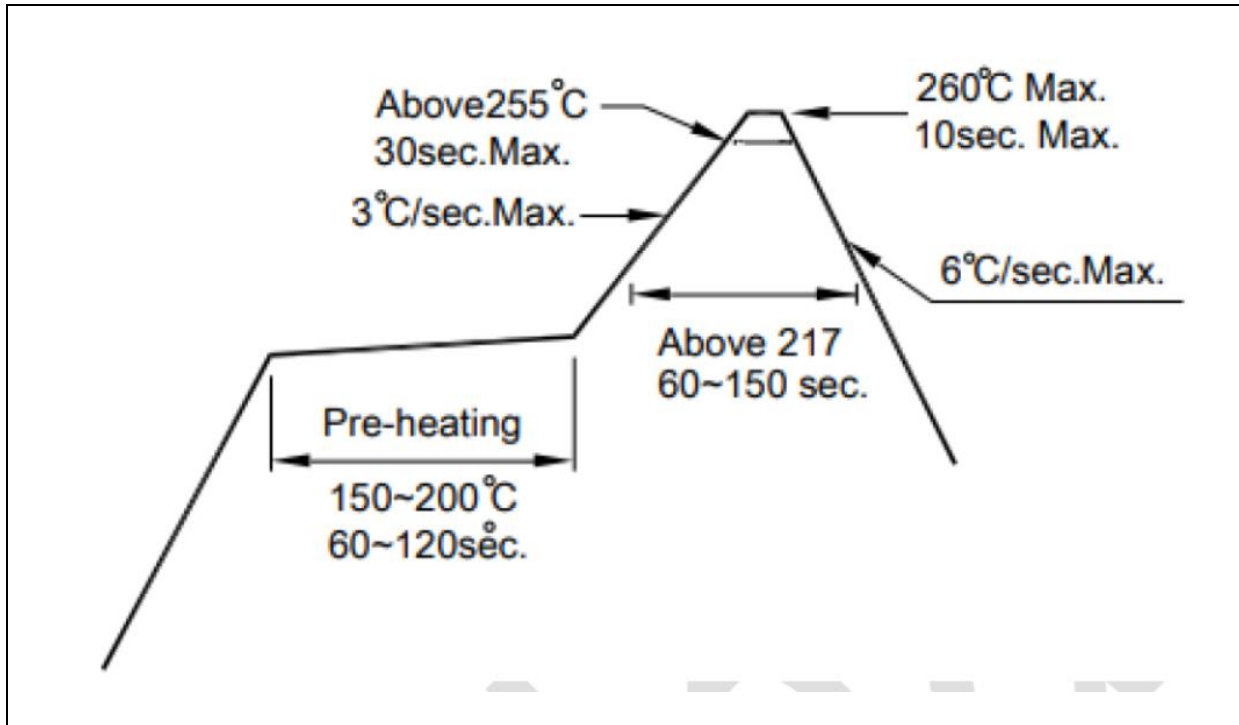
1. Dimensions are in millimetre (mm).
2. Tolerance  $\pm 0.1\text{mm}$  with angle tolerance  $\pm 0.5^\circ$ .

**ELECTRO-OPTICAL CHARACTERISTICS:**
**Relative Intensity v.s. Forward Current**

**Forward Current v.s. Forward Voltage**

**Max. Current v.s. Ambient Temperature**

**Relative Spectral Distribution**

**Directive Radiation**


## RECOMMENDED SOLDERING PROFILE:

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Lead-free Solder:

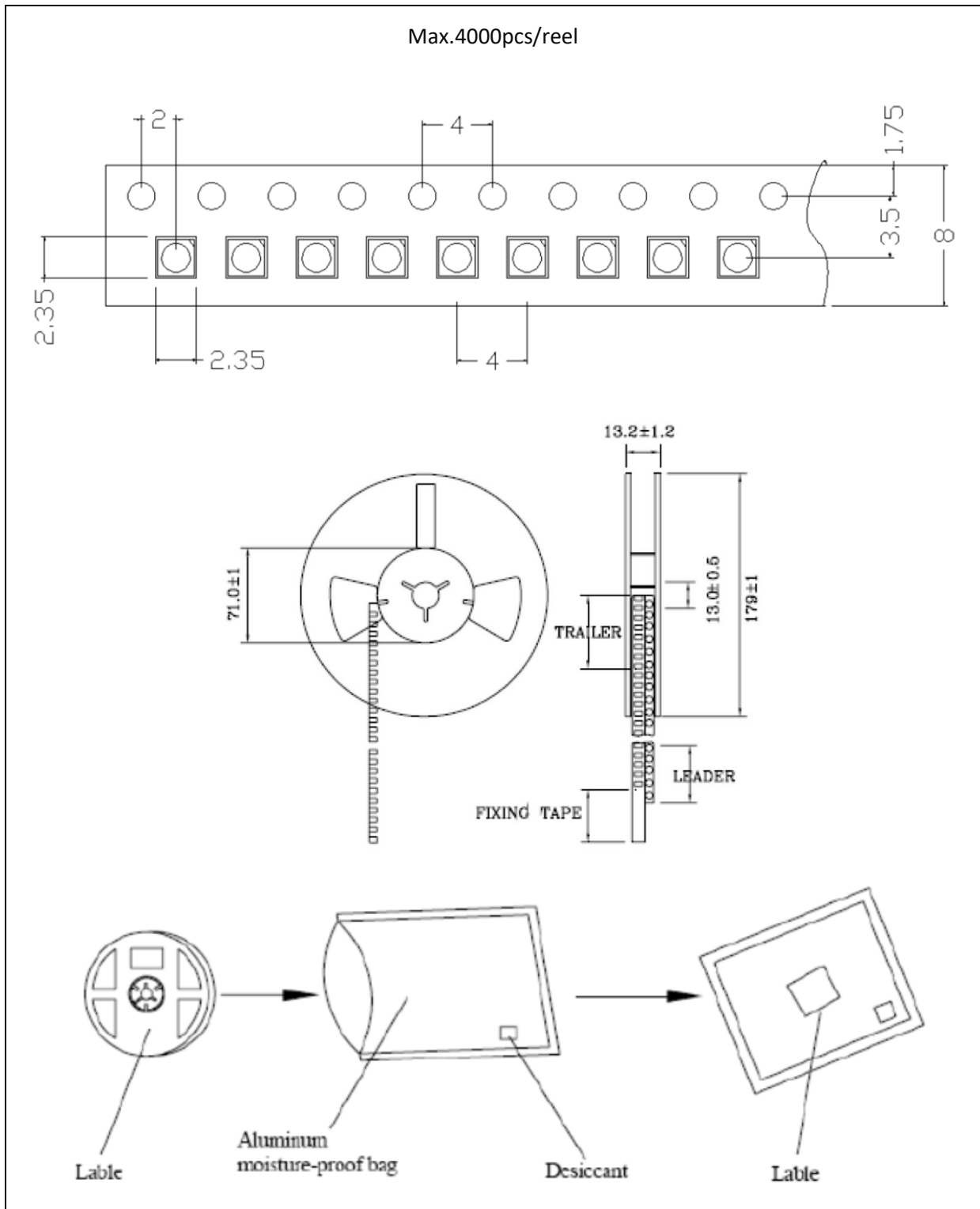


Note:

1. Maximum reflow soldering: 2 times.
2. Recommended reflow temperature is 240°C; the maximum soldering temperature should be limited to 260°C.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

## PACKING SPECIFICATION:

Reel Dimension:



## PRECAUTIONS OF USE:

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### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 24 hours. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

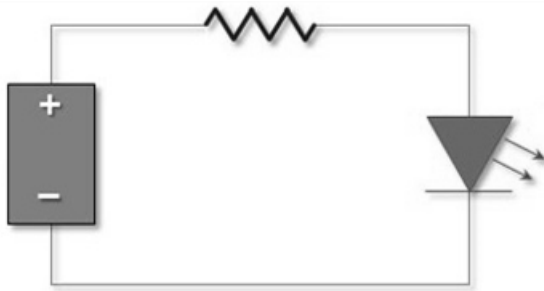
### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 48hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

### Testing Circuit:



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

**REVISION RECORD:**

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Version	Date	Summary of Revision
A1.0	15/10/2024	Datasheet set-up.